EUKUPEAN PAIENI UFFICE

Patent Abstracts of Japan

PUBLICATION NUMBER

: 08153971

PUBLICATION DATE

11-06-96

APPLICATION DATE

28-11-94

APPLICATION NUMBER

06293139

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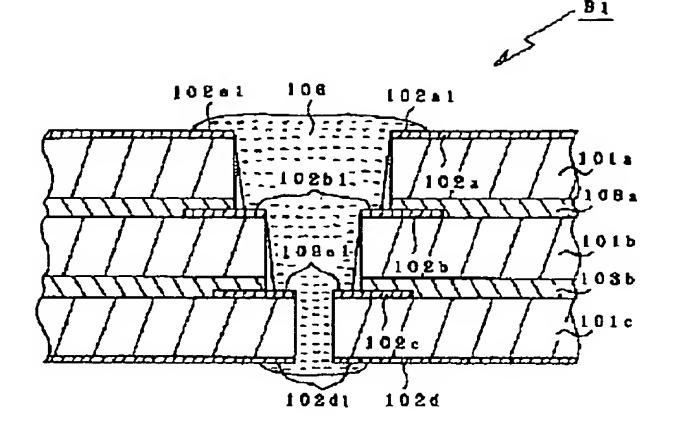
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TITLE

MULTILAYERED PRINTED WIRING

BOARD AND ITS MANUFACTURE



ABSTRACT: PURPOSE: To provide a multilayered printed wiring board in which the metallic wiring patterns of the laminated boards constituting the wiring board can be surely electrically connected to each other.

> CONSTITUTION: A through hole is formed through a multilayered wiring board BI manufactured by laminating a plurality of boards 101a-101c carrying metallic wiring patterns 102a-102d on their surfaces upon another by successively and continuously changing the diameter of the through hole from φ a to φ c at every board 101a-101c and the through hole is filled with conductive paste 106 over the full depth of the through hole from the surface of the board 101a to the bottom of the board 101c.

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